

JIEJIE MICROELECTRONICS CO., LTD.



Isolation Voltage	V_{iso}	5000 ^v	Vrms
Operating Temperature	T_{opr}	-40 ~ 110	°C
Junction Temperature	T_j	125	°C
Storage Temperature	T_{stg}	-40 ~ 125	°C
Soldering Temperature	T_{sol}	260	°C
Peak pulse voltage ($T = 25^{\circ}C$; non-repetitive, off-state)	V_{pp}	3	kV

1. Electrical Characteristics (at $T = 25^{\circ}C$)

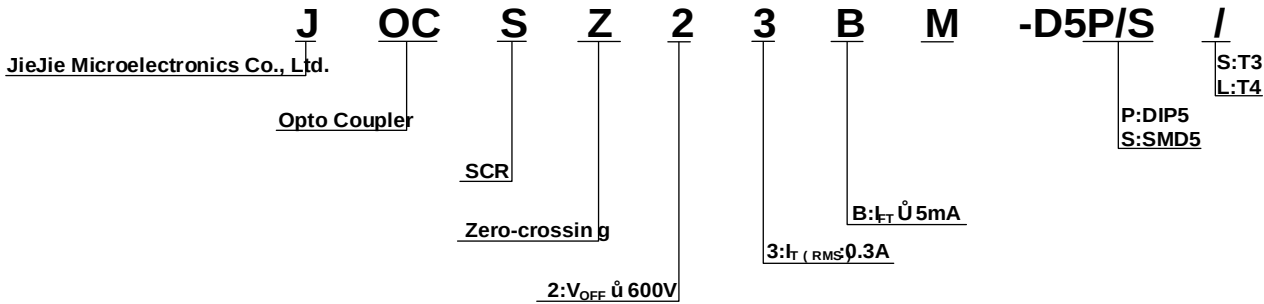
2. Thermal Characteristics

3. Mechanical Characteristics

Parameter Symbol Condition Min. Typ. Max.



h w59wLbD LbC h wa ! ¢ L h b



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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

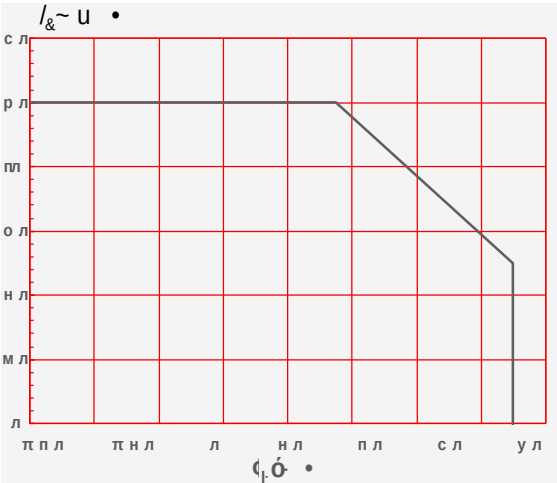


FIG.2: On-state Terminal Current vs. Ambient Temperature

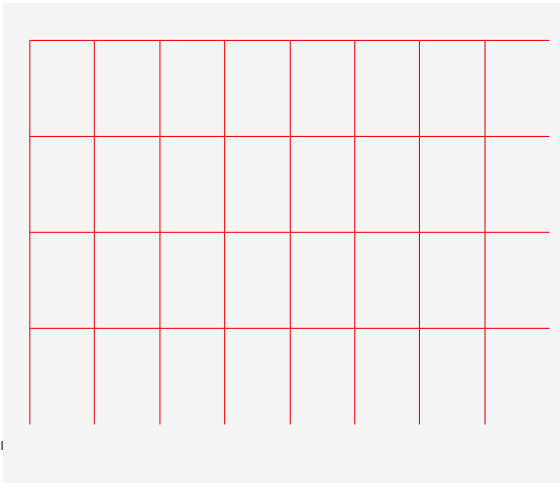


FIG.7: On-state characteristics

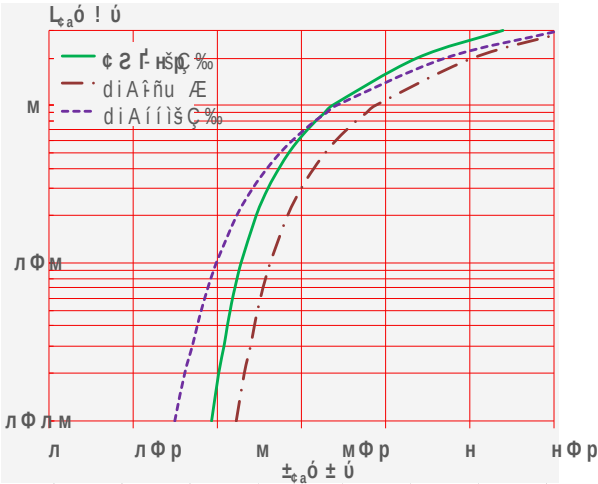


FIG.8: Normalized Holding Current vs. Ambient Temperature



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FIG.11: Test Circuits of Turn On Time

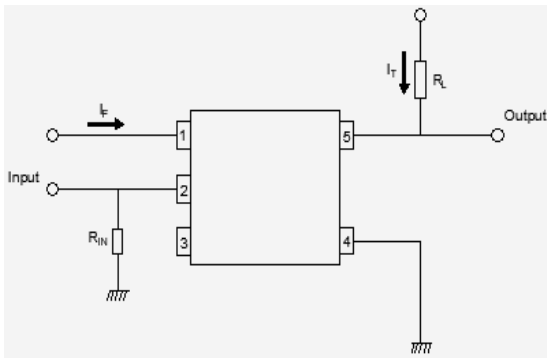


FIG.12: Wave forms of Turn On Time

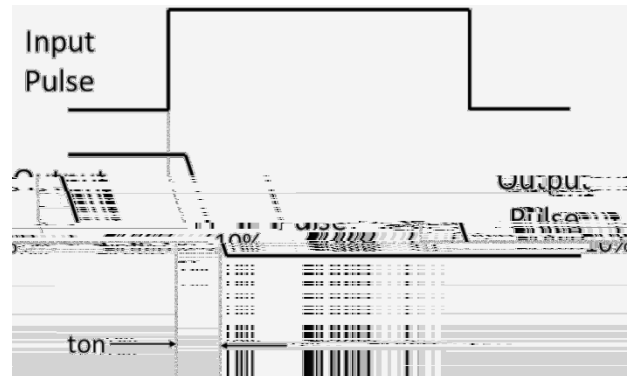
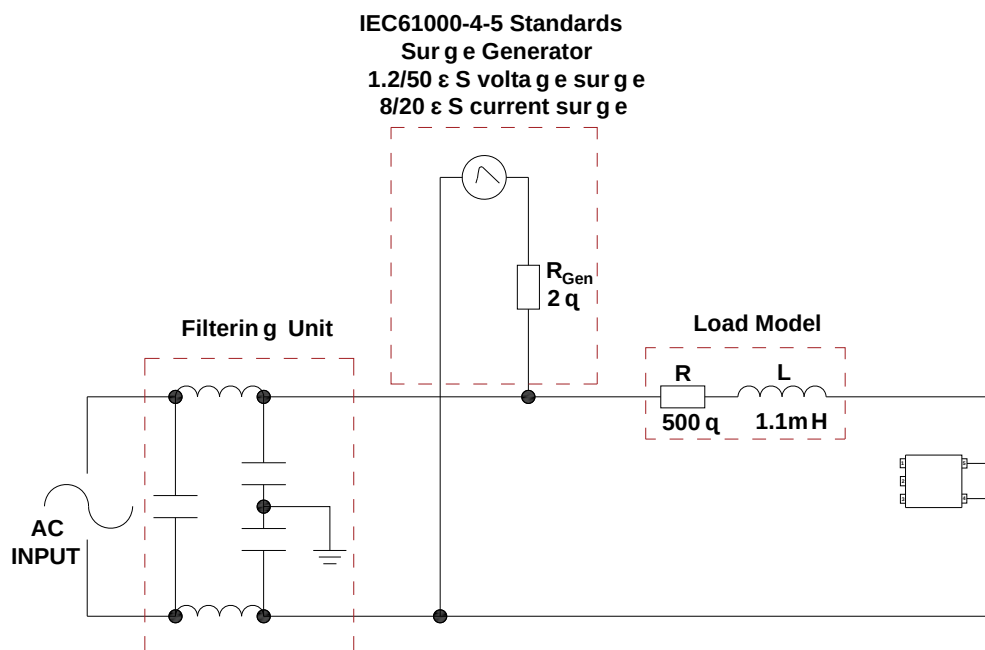
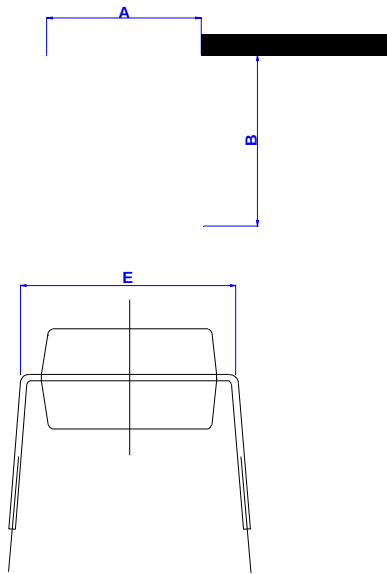


FIG.13: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards

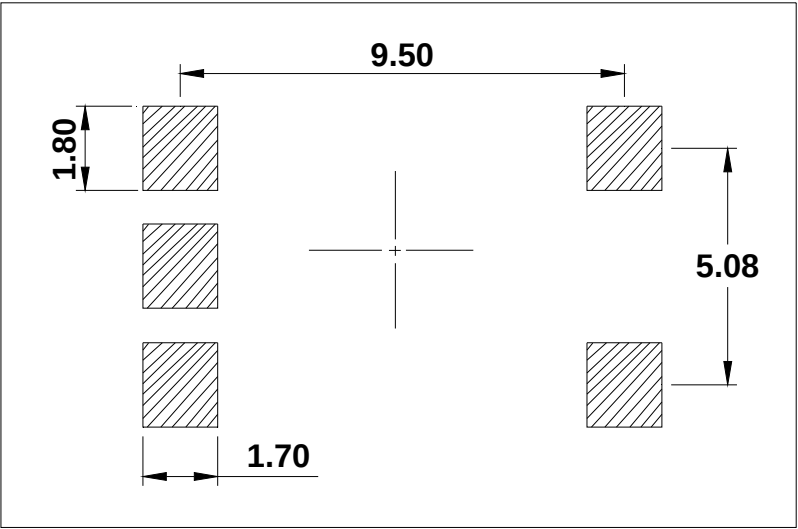


Standard DIP Type:



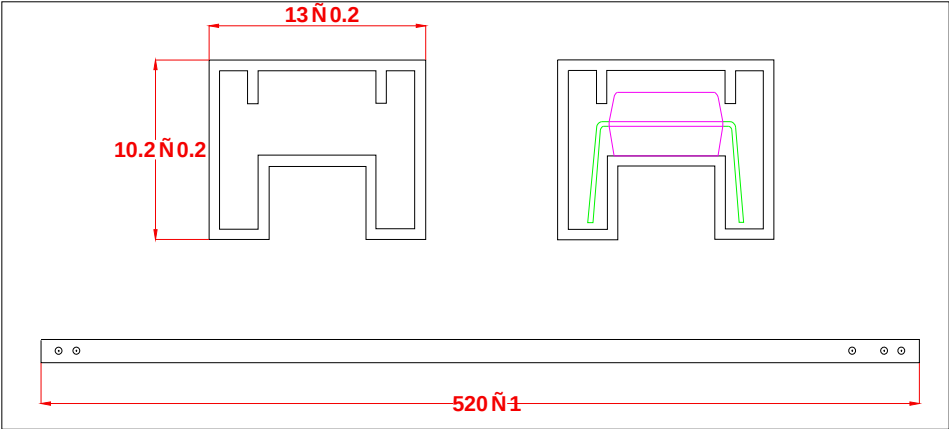
w9/h aa9b595 { h [59w a ! { Y ó5λ Y Ŝ y ă λ 2 y ă λ y Y \$ Ĥzú/ t Ŝ ă ă z

Option SMD



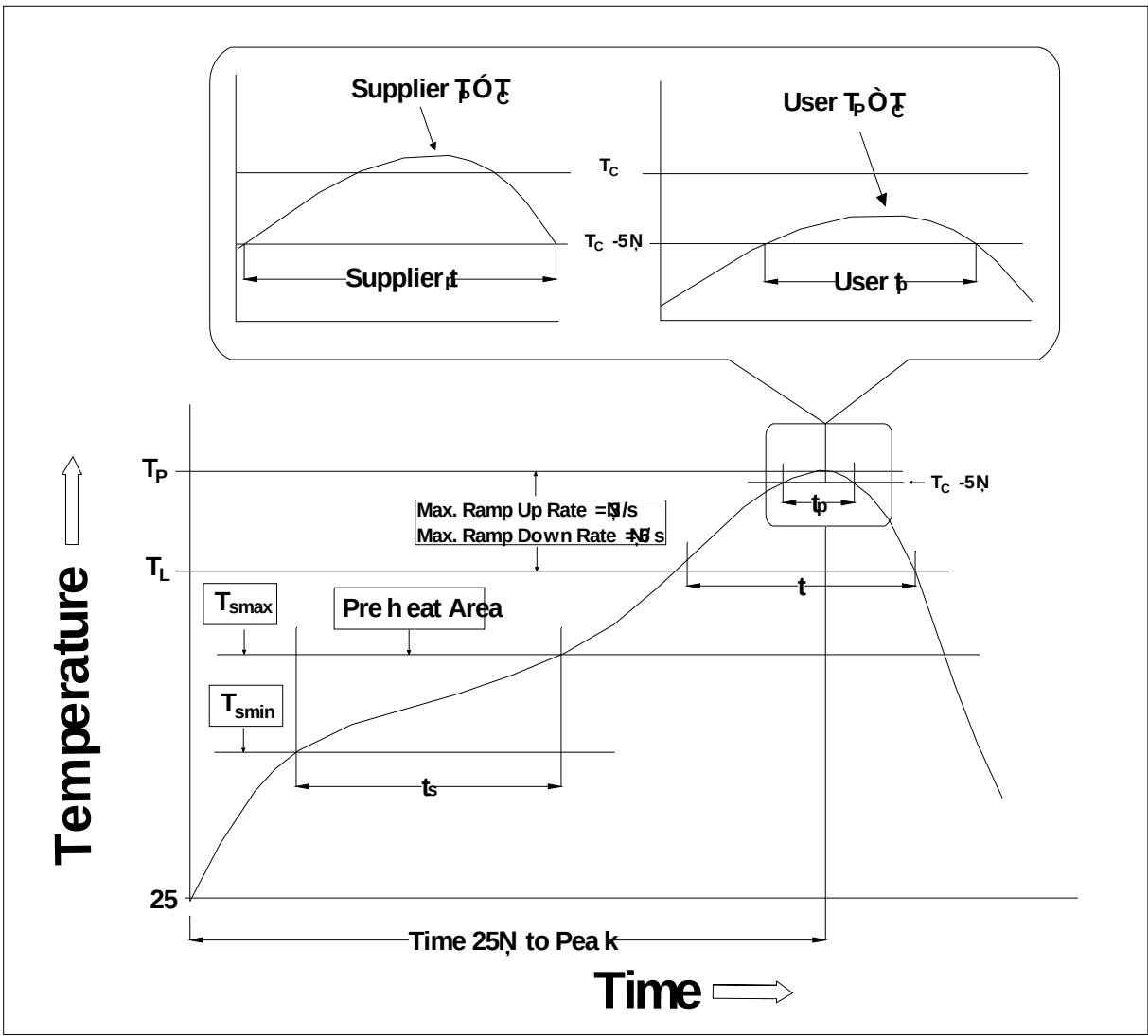
¢ | .9 { t9/LCL/ ! ¢ L h b { ó5λ Y Ŝ y ă λ 2 y ă λ y Y Y dz y t Ŝ ă ă z ú K Ŝ

Standard DIP



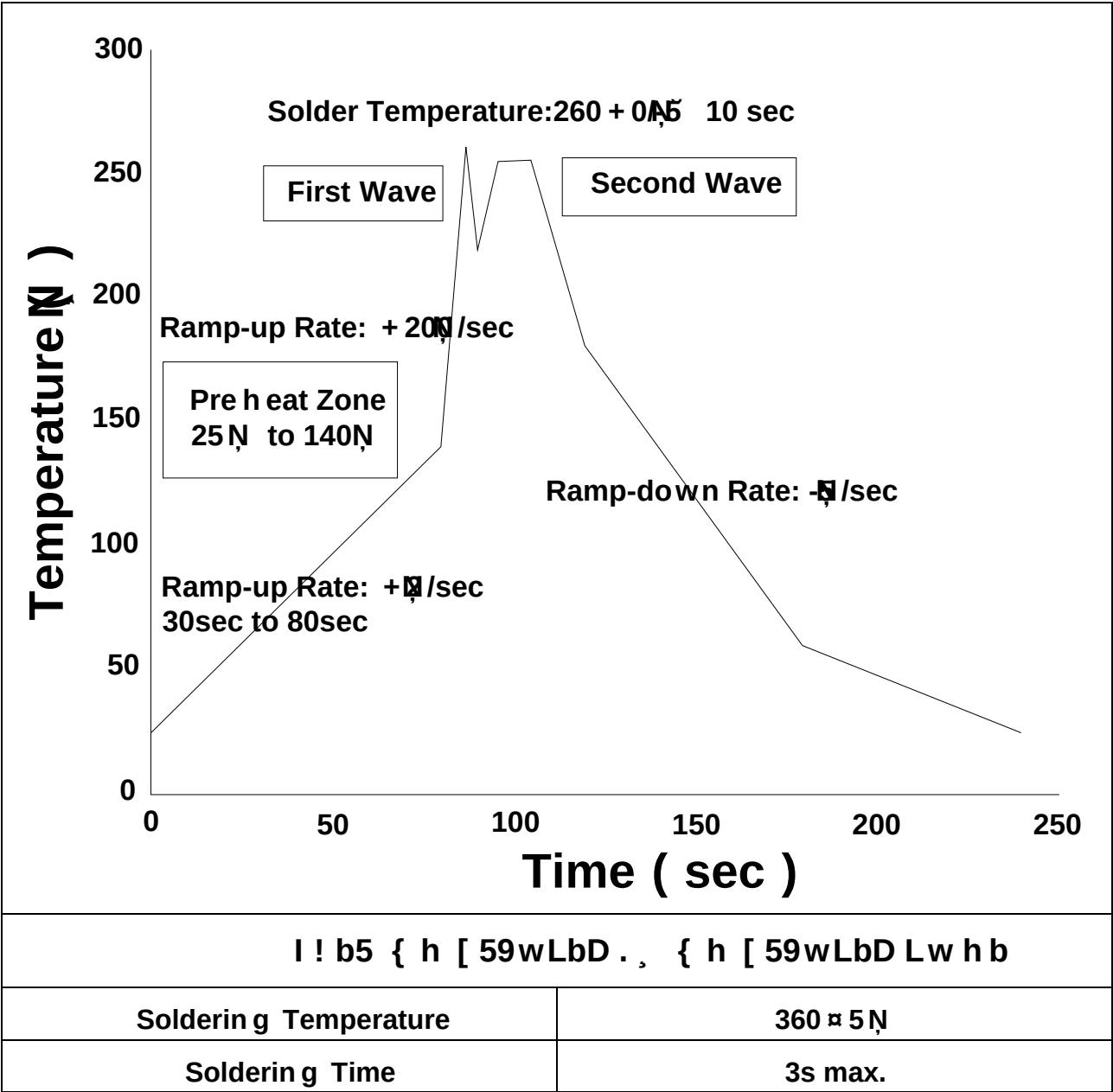
Re f .	Dimensions					
	Millimeters			Inc h es		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.70	16.00	16.30	0.618	0.630	0.642

w9C [h ² LbCh wa ! ¢ L h b



Temperature Min. (Tsmin)	150 N
Temperature Max. (Tsmax)	200 N
Time (ts) f rom (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3 N/second max.
Li q uidus Temperature (TL)	217 N
Time (tL) Maintained Above (TL)	60-120 seconds
Pea k Body Pac k a g e Temperature	260 N + 0 N / -5 N
Time (tP) wit h in d f 260 N	10 seconds
Ramp-down Rate (TP to TL)	6 N/second max.

2 ! ± 9 { h [59wLbD





Note:

1. Reflow soldering is recommended at the temperatures and time, no more than three times.